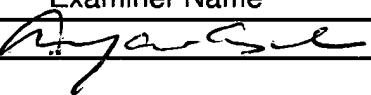


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

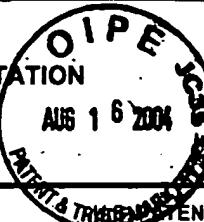
Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PARTIAL WAFER BONDING AND DICING						
Application Number :	10/710,880						
Confirmation Number:							
First Named Applicant:	Louis Hsu						
Attorney Docket Number:	FIS920040114US1						
Art Unit:							
Examiner:							
Search string:	(4962879 or 6004866 or 6010591 or 6013534 or 6538330 or 6616854).pn						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1A	1	4962879	1990-10-16	Gosele et al	—	—	—
1A	2	6004866	1999-12-21	Nakano et al	—	—	—
1A	3	6010591	2000-01-04	Gosele	—	—	—
1A	4	6013534	2000-01-11	Mountain	—	—	—
1A	5	6538330	2003-03-25	Forbes	—	—	—
1A	6	6616854	2003-09-09	Jones et al	—	—	—
Signature							
Examiner Name				Date			
				5/25/05			

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
FIS920040114US1APPLICATION NO.
10/710,880

Hsu et al.

FILING

Concurrently Herewith

GROUP ART

Unknown

PATENT & TRADEMARK DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
LT	WO9925019	05/20/99	International				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

PA	K. Gann, "High Density Packaging of Flash Memory", IEEE, 1998, pp. 96-98.
PA	V. Dragoi et al., "Reversible Wafer Bonding For Reliable Compound Semiconductor Processing", IEEE, 2002, pp. 331-334.

EXAMINER

DATE CONSIDERED

5/30/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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ATTY DOCKET NO.
FIS920040114US1

APPLICATION NO.

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FILING

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GROUP ART

Unknown

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

G. Reed, "Semiconductor Packaging", Semiconductor International, September, 2003, pp. 50.

EXAMINER

DATE CONSIDERED

5/30/05

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